

March 2013

# FQP13N50 / FQPF13N50

## **N-Channel QFET MOSFET**

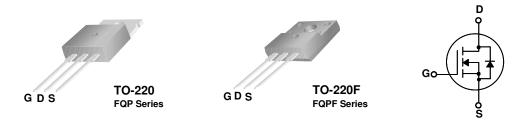
500 V, 12.5 A, 430 m $\Omega$ 

### **Description**

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor®'s proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

### **Features**

- 12.5 A, 500 V,  $R_{DS(on)}$  = 430 m $\Omega$  (Max) @ $V_{GS}$  = 10 V,  $I_D$  = 6.25 A
- Low Gate Charge (Typ. 45 nC)
- Low Crss (Typ. 25 pF)
- · 100% Avalanche Tested



## Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		FQP13N50	FQPF13N50	Unit
$V_{DSS}$	Drain-Source Voltage		500		٧
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C)		12.5	12.5 *	Α
	- Continuous (T <sub>C</sub> = 100°C)		7.9	7.9 *	Α
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	50	50 *	Α
V <sub>GSS</sub>	Gate-Source Voltage		± 30		V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	810		mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	12.5		Α
E <sub>AR</sub>	Repetitive Avalanche Energy (		17		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.5		V/ns
$P_D$	Power Dissipation (T <sub>C</sub> = 25°C)		170	56	W
	- Derate above 25°C		1.35	0.45	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150		°C
T <sub>L</sub>	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300		°C

<sup>\*</sup> Drain current limited by maximum junction temperature.

#### **Thermal Characteristics**

Symbol	Parameter	FQP13N50	FQPF13N50	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.74	2.23	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.5		°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Off Cha	aracteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	500			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C		0.48		V/°(
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V			1	μА
		V <sub>DS</sub> = 400 V, T <sub>C</sub> = 125°C			10	μА
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Cha	aracteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		5.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 6.25 \text{ A}$		0.33	0.43	Ω
9FS	Forward Transconductance	V <sub>DS</sub> = 50 V, I <sub>D</sub> = 6.25 A (Note 4)		10		S
C <sub>oss</sub>	Output Capacitance	f = 1.0 MHz		245	320	_
		†		=		
C <sub>rss</sub>	Reverse Transfer Capacitance			25	35	pF pF
	Reverse Transfer Capacitance ing Characteristics			=		
Switch	,	V <sub>DD</sub> = 250 V. I <sub>D</sub> = 13.4 A.		=		
Switch	ing Characteristics	$V_{DD} = 250 \text{ V}, I_{D} = 13.4 \text{ A},$ $R_{C} = 25 \Omega$		25	35	pF
Switch	ing Characteristics  Turn-On Delay Time	$V_{DD} = 250 \text{ V}, I_{D} = 13.4 \text{ A},$ $R_{G} = 25 \Omega$		25	35 90	pF
Switch t <sub>d(on)</sub> t <sub>r</sub> t <sub>d(off)</sub>	ing Characteristics Turn-On Delay Time Turn-On Rise Time	55		25 40 140	90 290	pF ns
Switch t <sub>d(on)</sub> t <sub>r</sub> t <sub>d(off)</sub>	ing Characteristics  Turn-On Delay Time  Turn-On Rise Time  Turn-Off Delay Time	$R_G = 25 \Omega$		25 40 140 100	90 290 210	ns ns
$\begin{array}{c} \textbf{Switch} \\ t_{d(on)} \\ t_r \\ t_{d(off)} \\ t_f \\ Q_g \end{array}$	ing Characteristics  Turn-On Delay Time  Turn-On Rise Time  Turn-Off Delay Time  Turn-Off Fall Time	$R_G = 25 \Omega$ (Note 4, 5)	  	25 40 140 100 85	90 290 210 180	ns ns ns
	ing Characteristics  Turn-On Delay Time  Turn-On Rise Time  Turn-Off Delay Time  Turn-Off Fall Time  Total Gate Charge	$R_{G} = 25 \ \Omega$ (Note 4, 5) $V_{DS} = 400 \ V, \ I_{D} = 13.4 \ A,$	   	40 140 100 85 45	90 290 210 180 60	ns ns ns
Switch  t <sub>d(on)</sub> t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub> Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	ing Characteristics  Turn-On Delay Time  Turn-On Rise Time  Turn-Off Delay Time  Turn-Off Fall Time  Total Gate Charge  Gate-Source Charge  Gate-Drain Charge	$R_{G} = 25 \ \Omega$ (Note 4, 5) $V_{DS} = 400 \ V, \ I_{D} = 13.4 \ A,$ $V_{GS} = 10 \ V$ (Note 4, 5)	  	25 40 140 100 85 45 11	90 290 210 180 60	ns ns ns ns
Switch  t <sub>d(on)</sub> t <sub>r</sub> t <sub>d(off)</sub> t <sub>f</sub> Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub> Drain-S	ing Characteristics  Turn-On Delay Time  Turn-On Rise Time  Turn-Off Delay Time  Turn-Off Fall Time  Total Gate Charge  Gate-Source Charge	$R_G = 25~\Omega \label{eq:RG}$ (Note 4, 5) $V_{DS} = 400~V, I_D = 13.4~A, \label{eq:VGS}$ (Note 4, 5) $V_{GS} = 10~V \label{eq:VGS}$ (Note 4, 5)	  	25 40 140 100 85 45 11	90 290 210 180 60	ns ns ns ns
Switch  td(on)  tr  td(off)  tf  Qg  Qgs  Qgd  Drain-S	ing Characteristics  Turn-On Delay Time  Turn-On Rise Time  Turn-Off Delay Time  Turn-Off Fall Time  Total Gate Charge  Gate-Source Charge  Gate-Drain Charge	$R_{G} = 25 \ \Omega$ (Note 4, 5) $V_{DS} = 400 \ V, I_{D} = 13.4 \ A,$ $V_{GS} = 10 \ V$ (Note 4, 5) $N_{GS} = 10 \ V$ (Note 4, 5) $N_{GS} = 10 \ V$	   	25 40 140 100 85 45 11 22	90 290 210 180 60	ns ns ns ns
Switch  td(on) tr  td(off) tf Qg Qgs Qgd  Drain-S	ing Characteristics  Turn-On Delay Time  Turn-On Rise Time  Turn-Off Delay Time  Turn-Off Fall Time  Total Gate Charge  Gate-Source Charge  Gate-Drain Charge  Source Diode Characteristics and Maximum Continuous Drain-Source Diode	$R_{G} = 25 \ \Omega$ $V_{DS} = 400 \ V, I_{D} = 13.4 \ A,$ $V_{GS} = 10 \ V$ $(Note 4, 5)$ $Note 5$ $Note 6$ $Note 6, 7$ $Note 7$ $Note 7$ $Note 7$ $Note 8$ $Note 8$ $Note 9$ $Note$		25 40 140 100 85 45 11 22	90 290 210 180 60 	ns ns ns ns nc nc
Switch  td(on) tr  td(off) tf Qg Qgs Qgd  Drain-S	ing Characteristics  Turn-On Delay Time  Turn-On Rise Time  Turn-Off Delay Time  Turn-Off Fall Time  Total Gate Charge  Gate-Source Charge  Gate-Drain Charge  Source Diode Characteristics al  Maximum Continuous Drain-Source Diode Maximum Pulsed Drain-Source Diode F	$R_{G} = 25 \ \Omega$ (Note 4, 5) $V_{DS} = 400 \ V, I_{D} = 13.4 \ A,$ $V_{GS} = 10 \ V$ (Note 4, 5) $N_{GS} = 10 \ V$ (Note 4, 5) $N_{GS} = 10 \ V$	   	25 40 140 100 85 45 11 22	90 290 210 180 60   12.5 50	ns ns ns nc nc

- **Notes:** 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 9.3mH,  $I_{AS} = 12.5A, V_{DD} = 50V, R_G = 25 \,\Omega,$  Starting  $T_J = 25^{\circ}C$  3.  $I_{SD} \leq 13.4A,$  di/dt  $\leq 200A/\mu s, V_{DD} \leq BV_{DSS},$  Starting  $T_J = 25^{\circ}C$  4. Pulse Test : Pulse width  $\leq 300\mu s,$  Duty cycle  $\leq 2\%$  5. Essentially independent of operating temperature

## **Typical Characteristics**

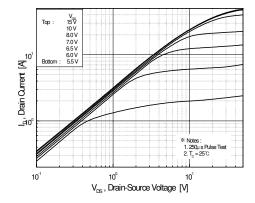


Figure 1. On-Region Characteristics

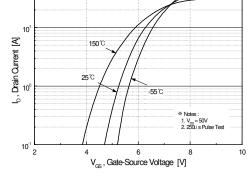


Figure 2. Transfer Characteristics

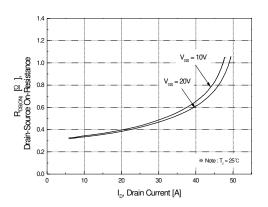


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

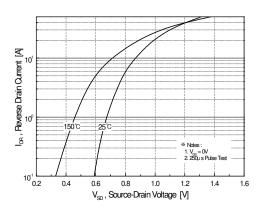


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

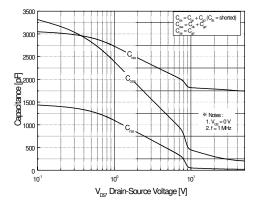


Figure 5. Capacitance Characteristics

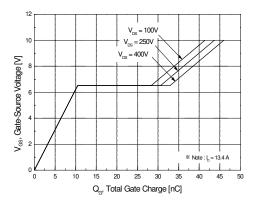


Figure 6. Gate Charge Characteristics

## Typical Characteristics (Continued)

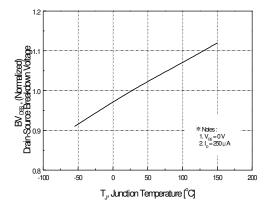


Figure 7. Breakdown Voltage Variation vs. Temperature

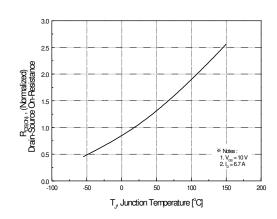


Figure 8. On-Resistance Variation vs. Temperature

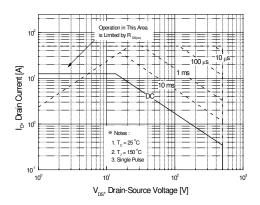


Figure 9-1. Maximum Safe Operating Area for FQP13N50

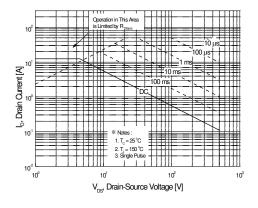


Figure 9-2. Maximum Safe Operating Area for FQPF13N50

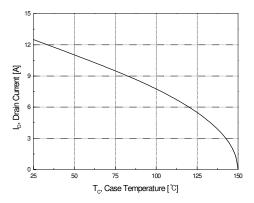


Figure 10. Maximum Drain Current vs. Case Temperature

## Typical Characteristics (Continued)

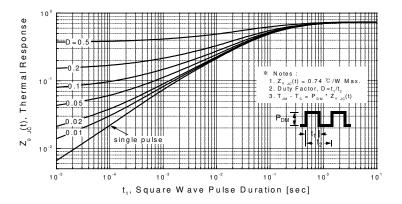


Figure 11-1. Transient Thermal Response Curve for FQP13N50

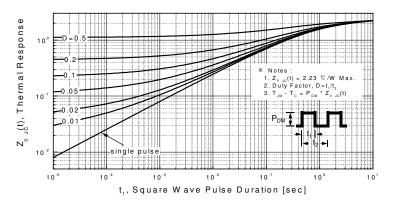
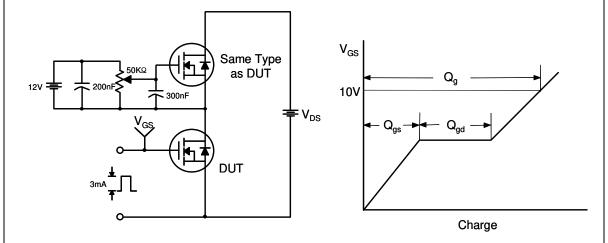
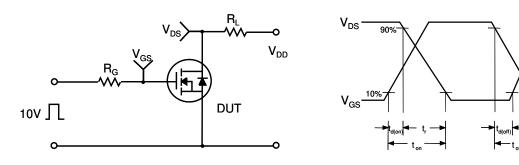


Figure 11. Transient Thermal Response Curve for FQPF13N50

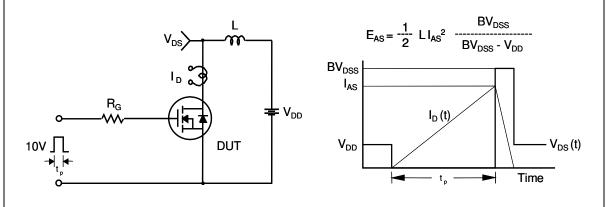
#### **Gate Charge Test Circuit & Waveform**



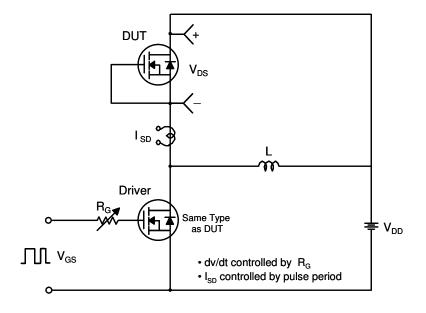
### **Resistive Switching Test Circuit & Waveforms**

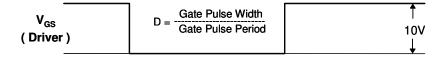


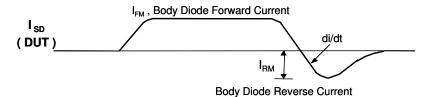
### **Unclamped Inductive Switching Test Circuit & Waveforms**

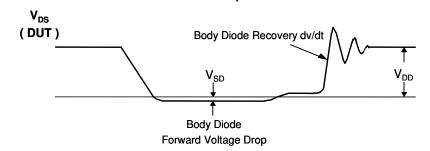


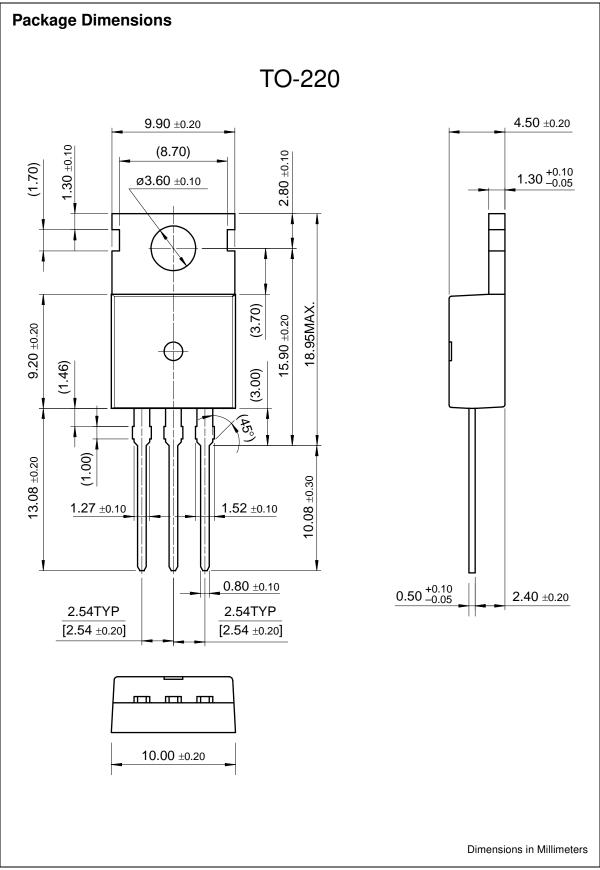
#### Peak Diode Recovery dv/dt Test Circuit & Waveforms

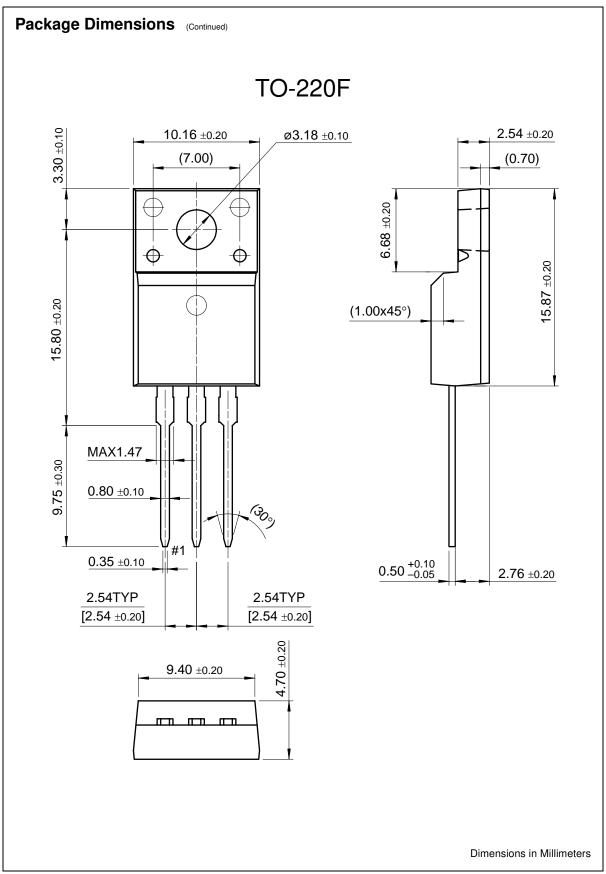
















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